

We2E-2

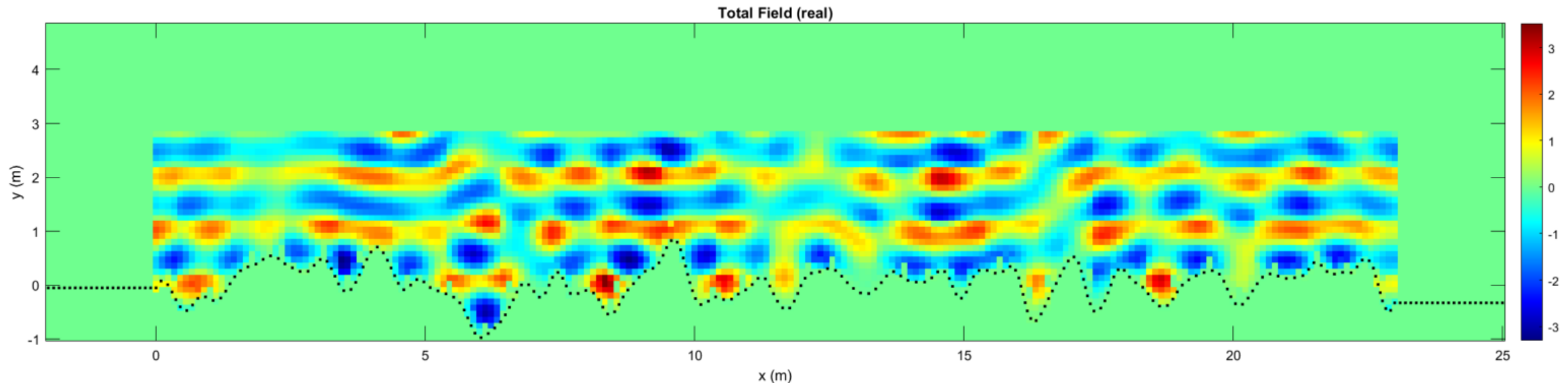
# An Effective Surface Impedance Concept to Model Arbitrary Roughness Profiles on Printed Circuit Boards up to 110 GHz

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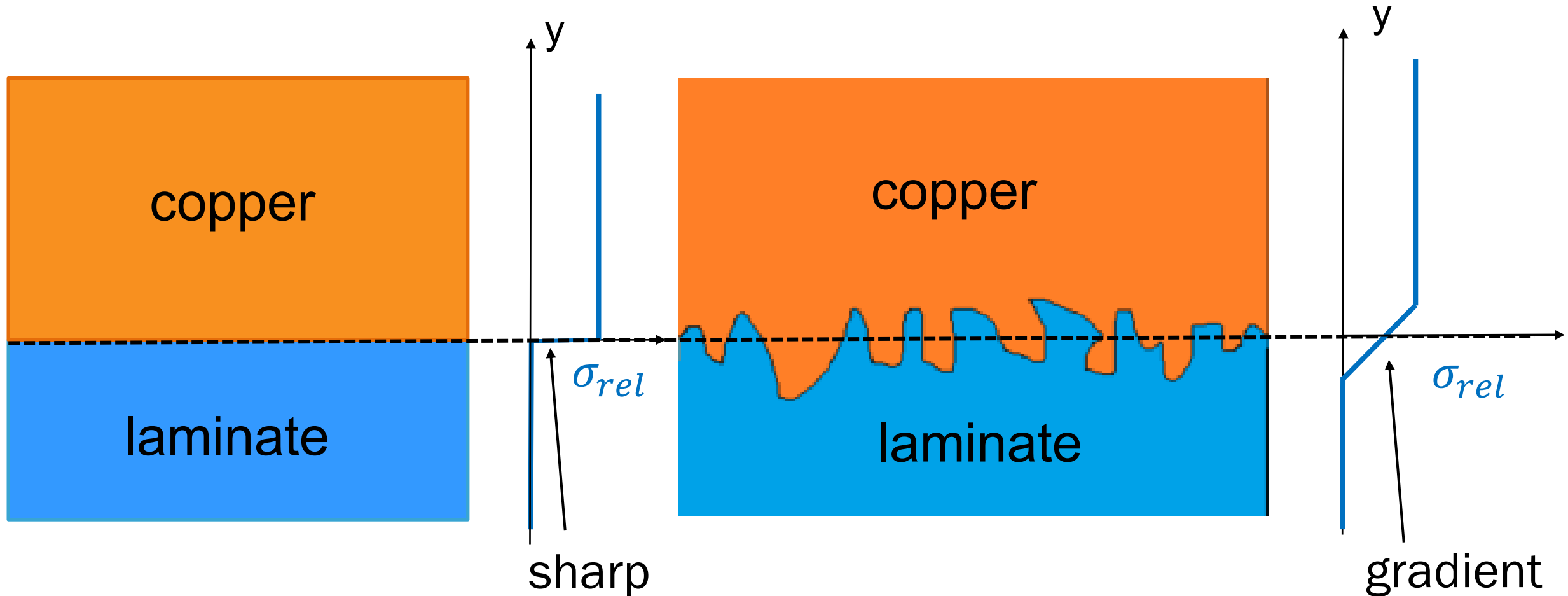
<sup>2</sup> Rohde & Schwarz GmbH & Co. KG, Teisnach, Germany

- Many ways to describe impact of rough surfaces on high-frequency signals.
- Famous: H&J, Huray (snowball), full-wave stochastic models, Gradient Model



# Gradient Model

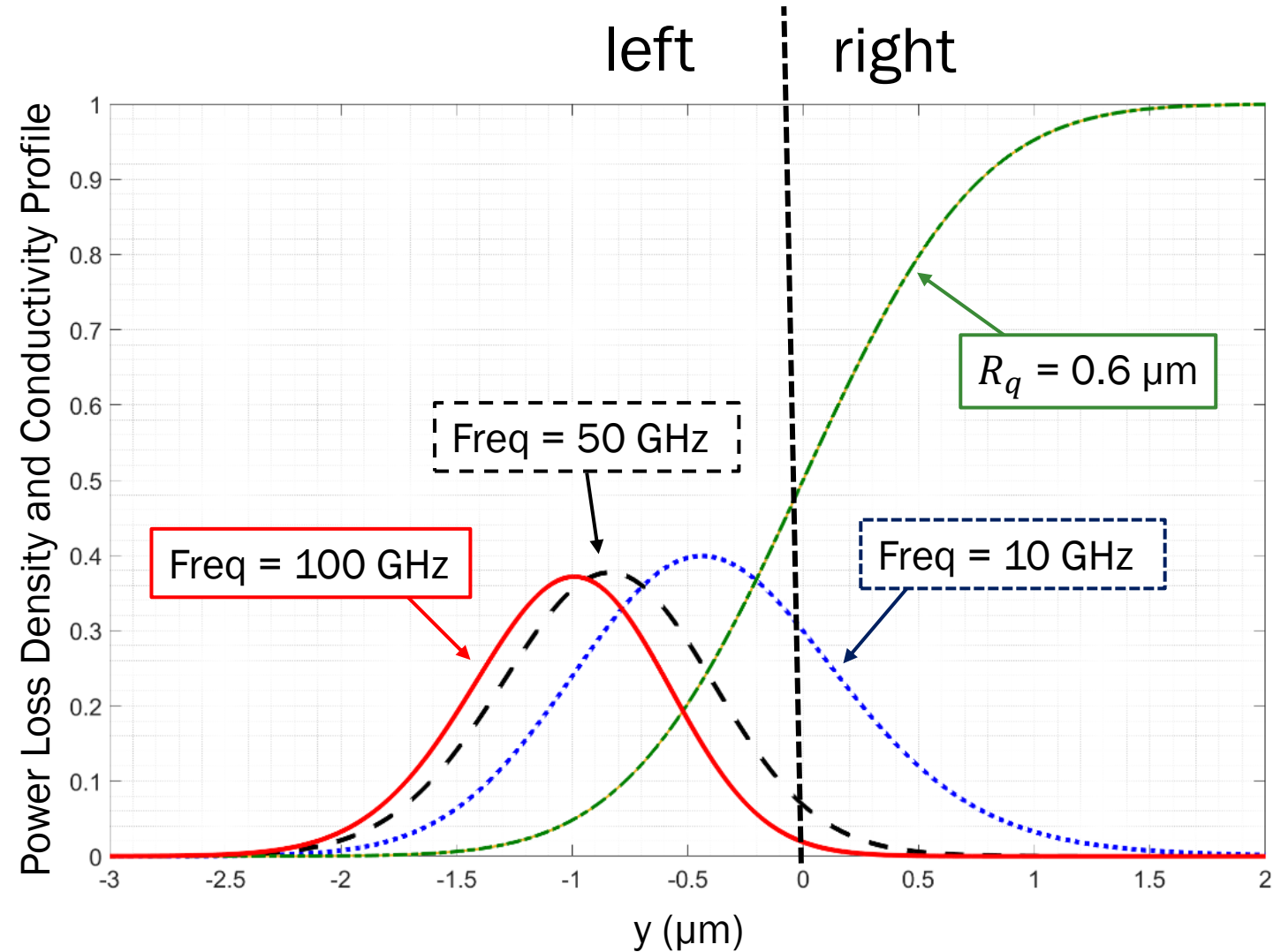
Classic skin effect:  Gradient Model:

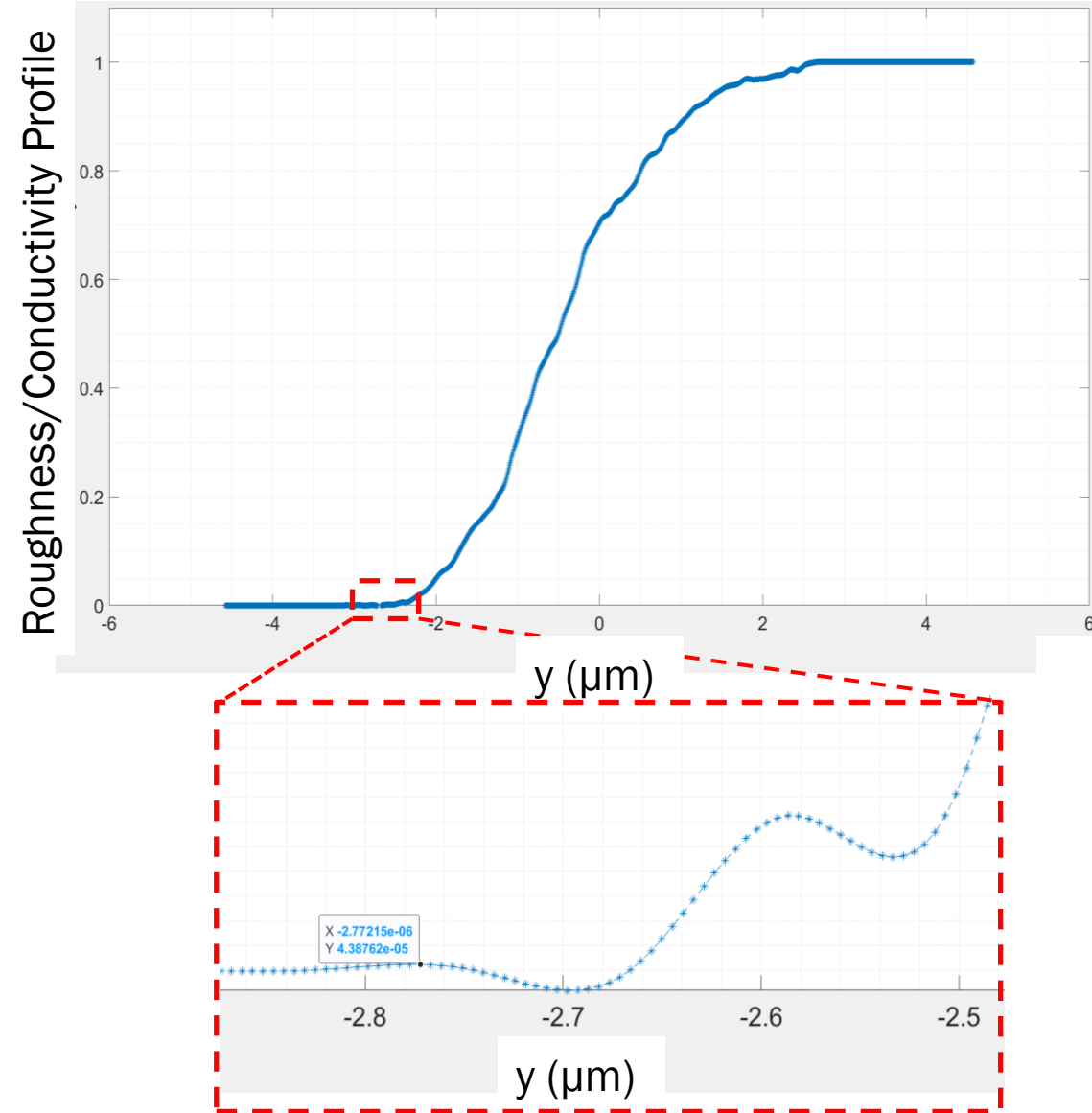


# Typical Profile Approximation

Roughness profiles often approximated as CDF of a gaussian bell curve with gradient  $R_q$ :

Most of the power loss on left side of Profile!





original:

$$\frac{\partial^2 \underline{B}_x^L}{\partial y^2} - j\omega\mu\sigma \underline{B}_x^L - \frac{\partial}{\partial y} \boxed{\ln(\sigma(y))} \frac{\partial \underline{B}_x^L}{\partial y} = 0$$

$$\ln(0) = -\text{inf} !!$$

## E-field formular:

$$\frac{\partial^2 \underline{E}_x^L}{\partial y^2} - j\omega\mu\sigma(y)\underline{E}_x^L = 0$$

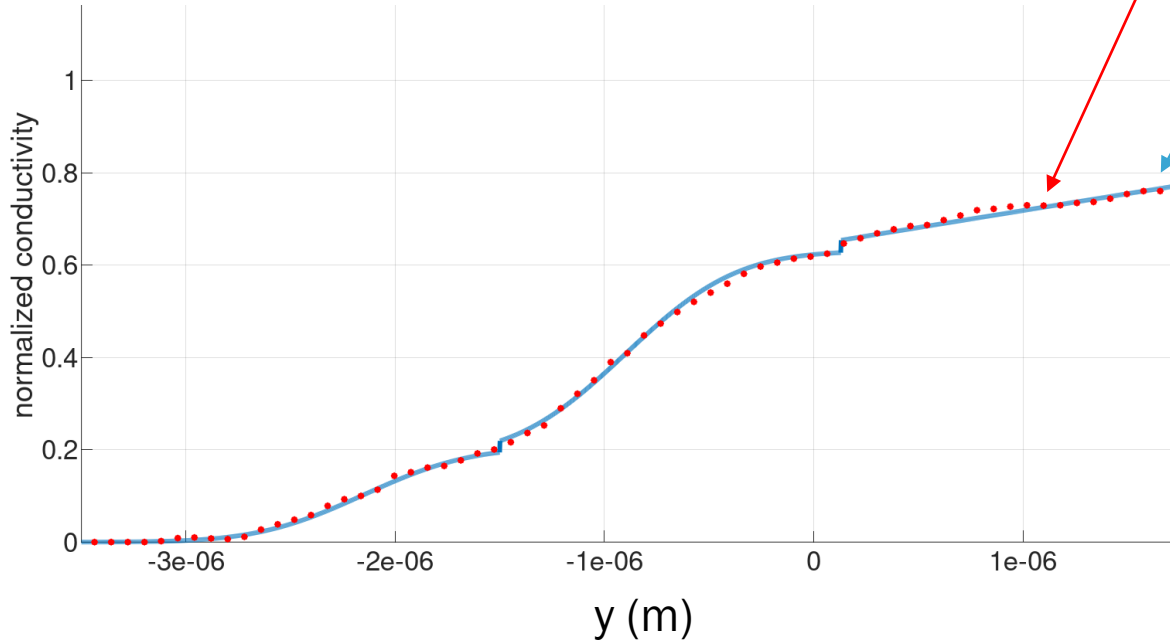
$$\left. \begin{array}{l} \text{power loss: } P_v = \int \sigma(y) |\underline{E}_x^L|^2 dy \\ \text{current: } \underline{I} = \int \sigma(y) \underline{E}_x^L dy \end{array} \right\} \underline{R} = \frac{P_v}{\underline{I}^2}$$

# Effective $R_q$ Concept

Calculate  $\underline{R}$  for a given profile and desired frequency

Estimate, which gaussian CDF with gradient  $R_{q,eff}$  has same  $\underline{R}$  as calculated from the real profile

cross-section:



Measurement

Approximation with 3 gaussian CDFs

Fit with single, gaussian CDF

$$R_q = \sqrt{\frac{1}{L} \int_0^L h(x)^2 dx}$$

$$R_{q,eff,single\ CDF} = 2.39\ \mu m$$

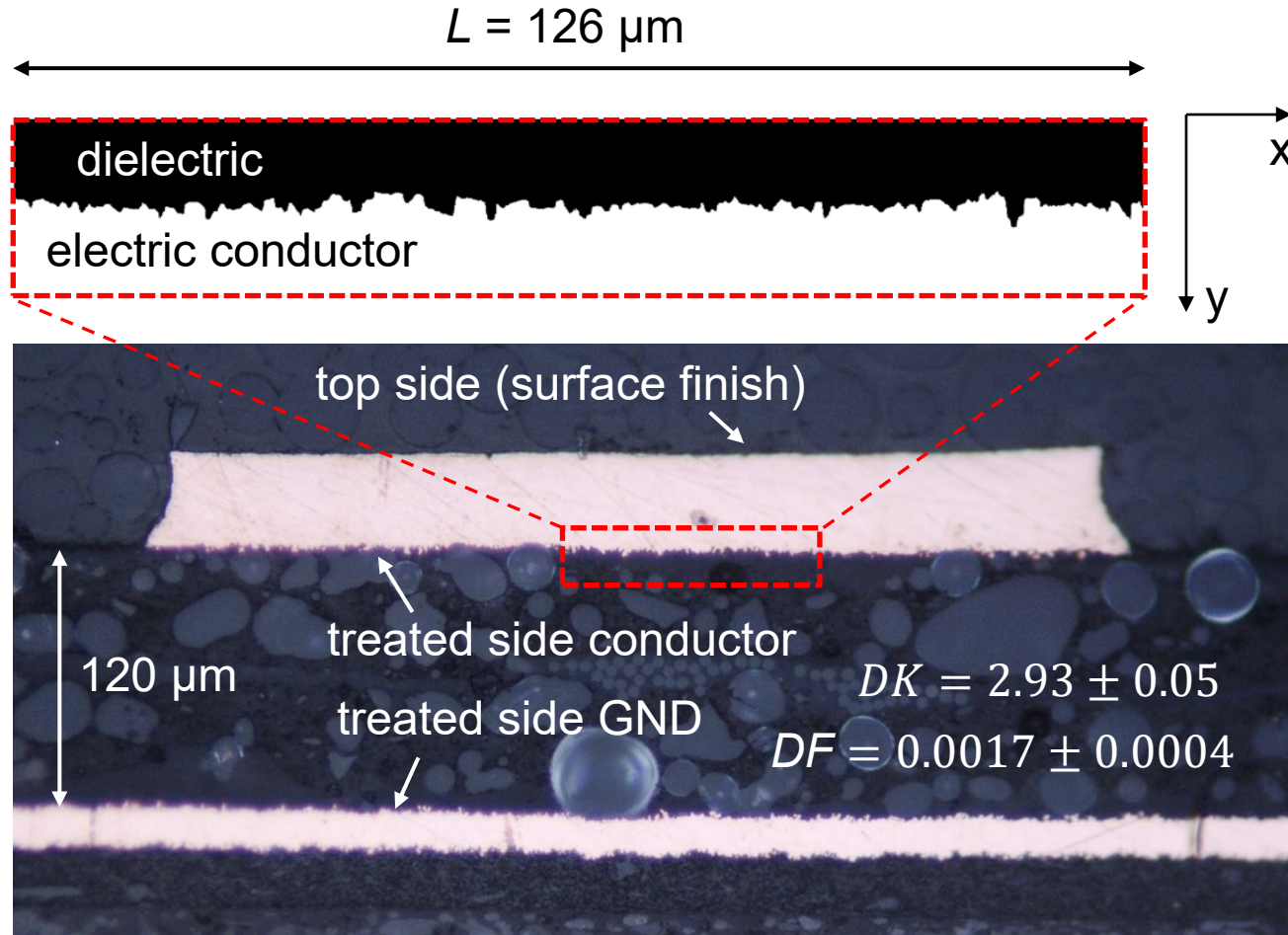
$$R_{q,eff\ DIN\ EN\ ISO\ 4287} = 2.45\ \mu m$$

$$R_{q,eff,three\ CDF} = 0.74\ \mu m$$

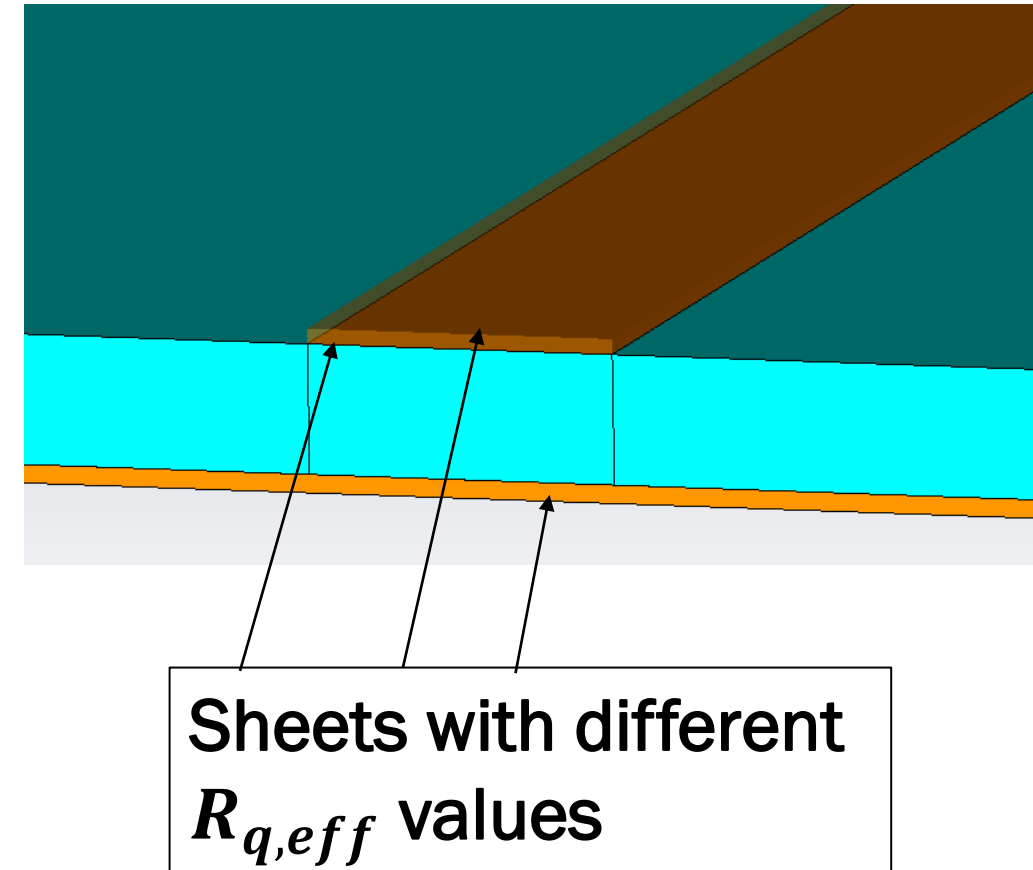
3 different approximations with total different results (@ 50 GHz)!!



## Real world Microstrip Line (cross-section):

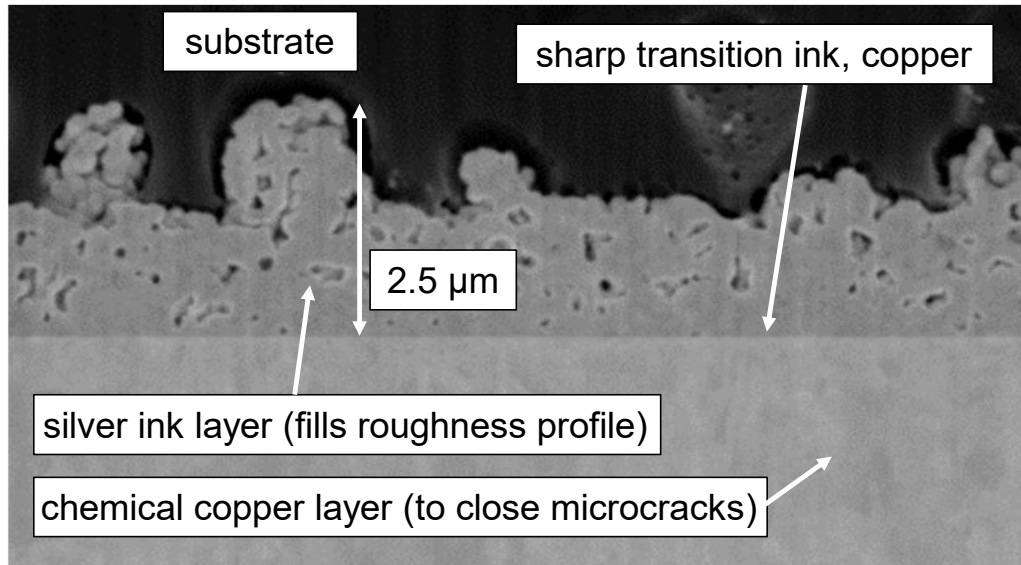


## Simulation model:

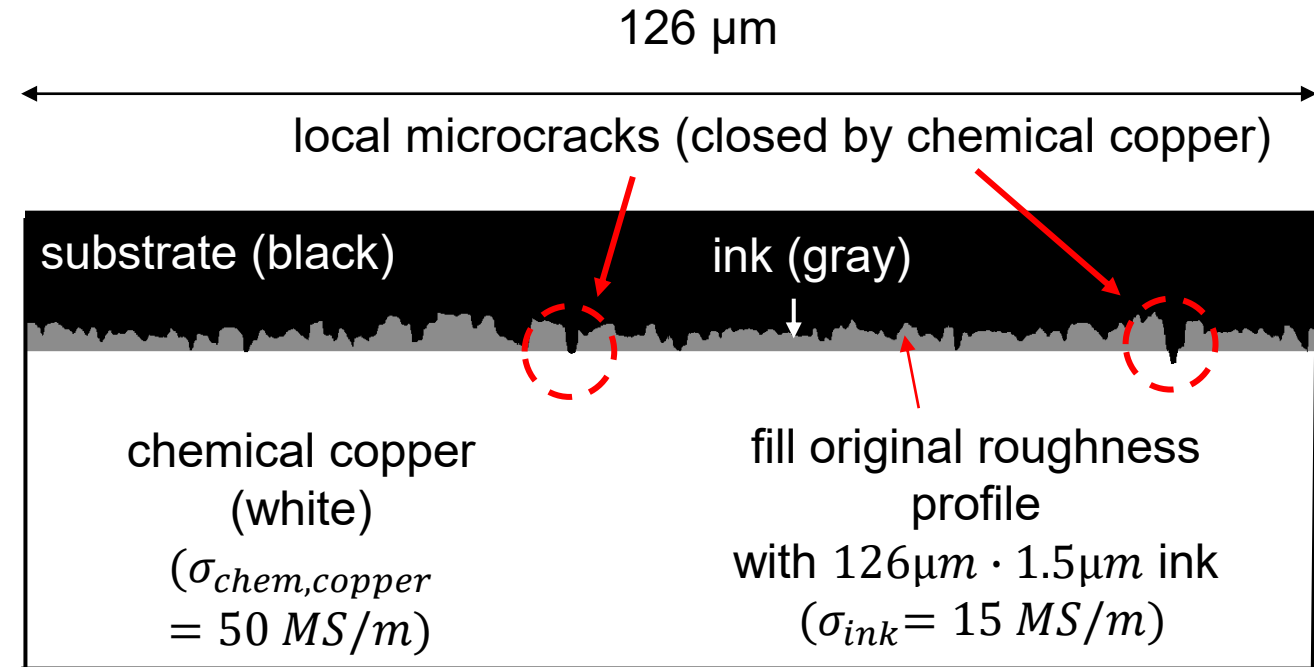




## FIB-Cut of an ink/chemical copper layer-stack:



model:



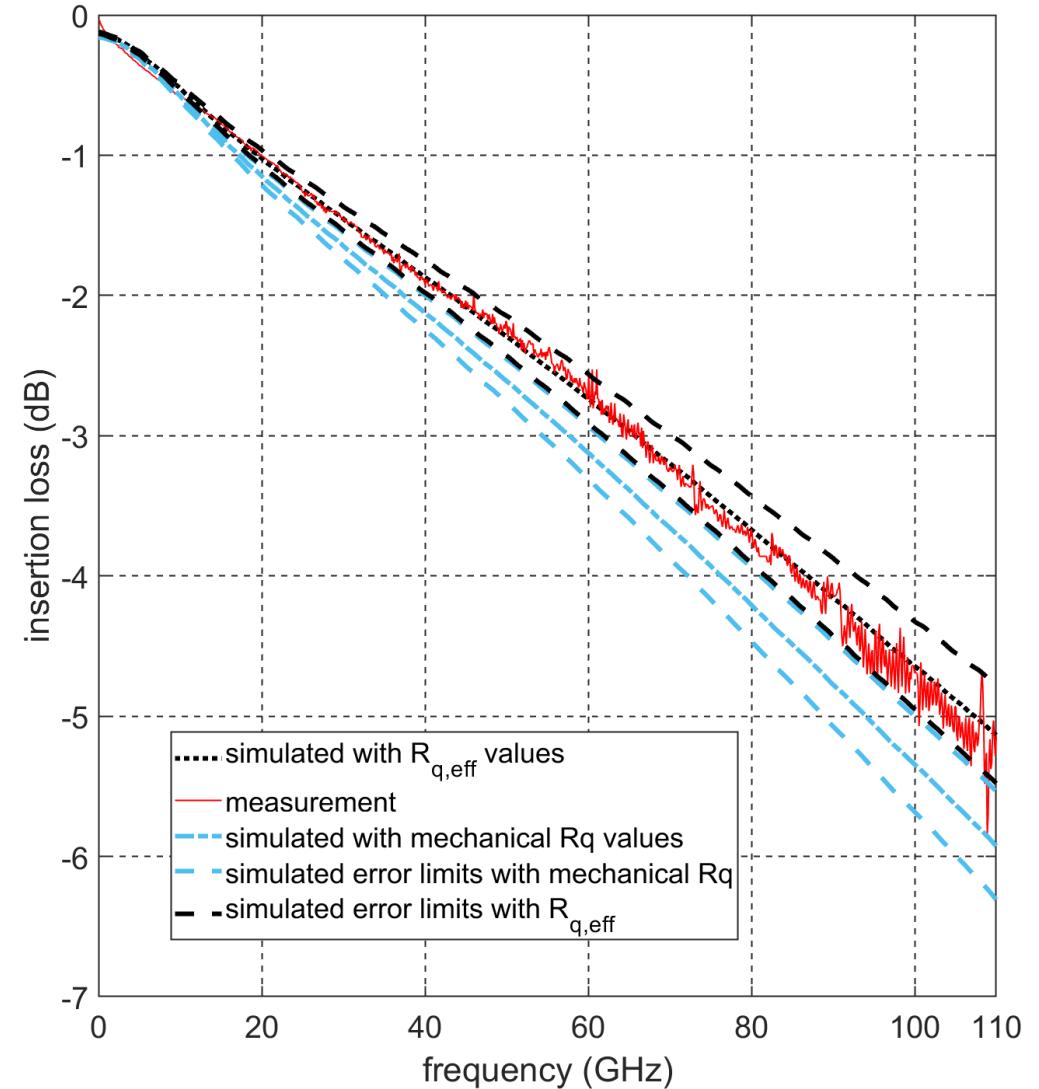
Conductor = pure copper (trace height = 50  $\mu\text{m}$ ):

$$R_{q,treated,side} = \sqrt{\frac{1}{L} \int_0^L h(x)^2 dx} = 0.85 \mu\text{m} \pm 0.1 \mu\text{m}$$

$$R_{q,eff,treated side} = 0.65 \mu\text{m} \pm 0.1 \mu\text{m}$$

$$R_{q,eff,top side} = 0.25 \mu\text{m} \pm 0.05 \mu\text{m}$$

Only with  $R_{q,eff}$  plausible simulation results!!

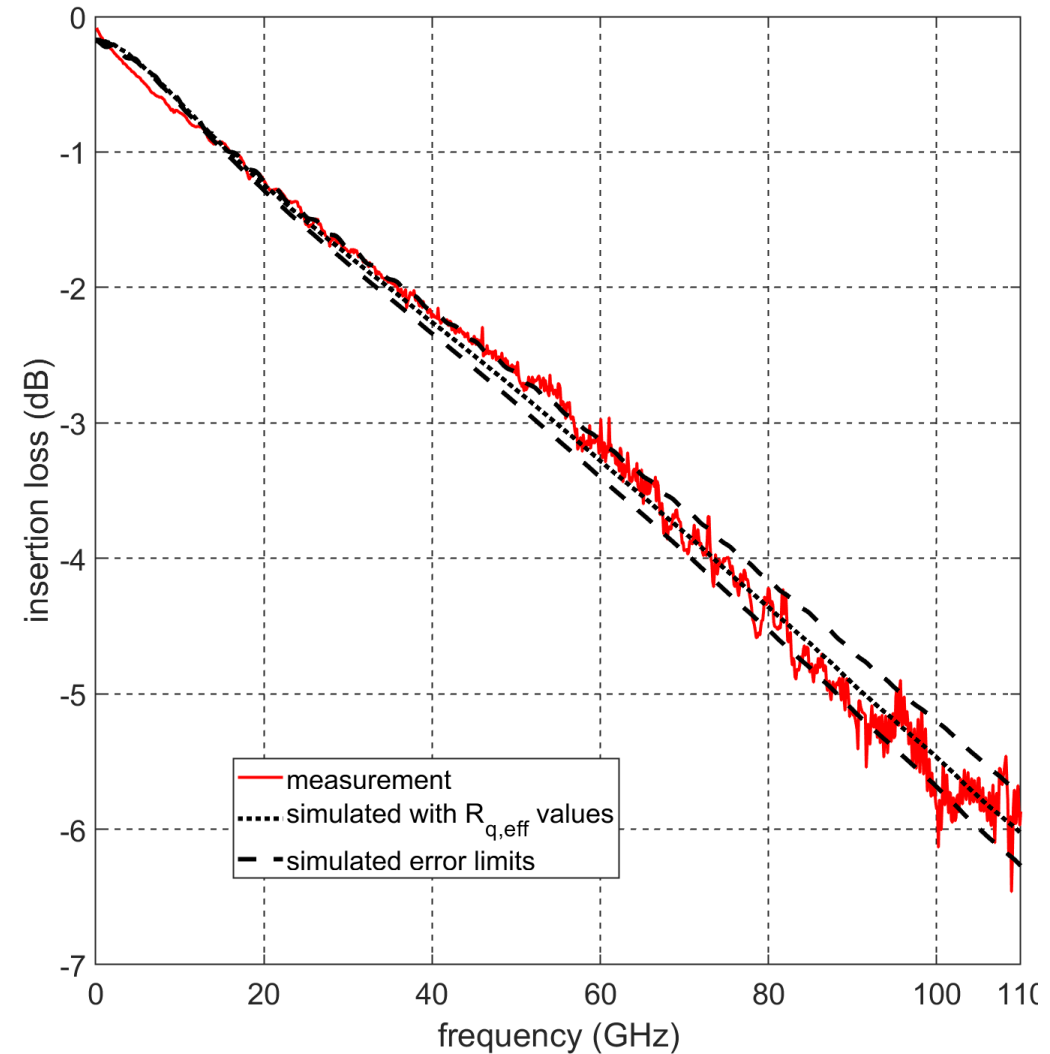


Conductor = ink/chem. Copper  
layerstack (trace height =  $5\mu\text{m}$ ):

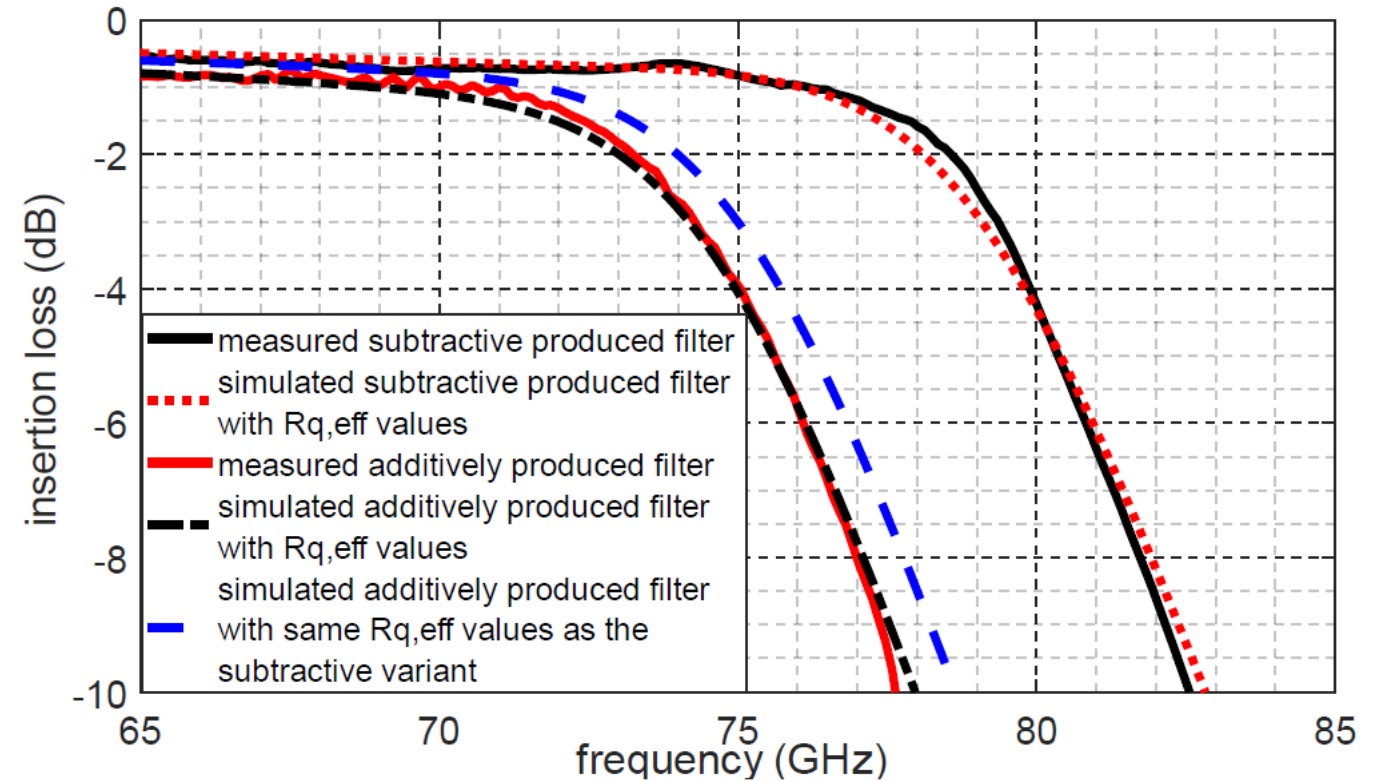
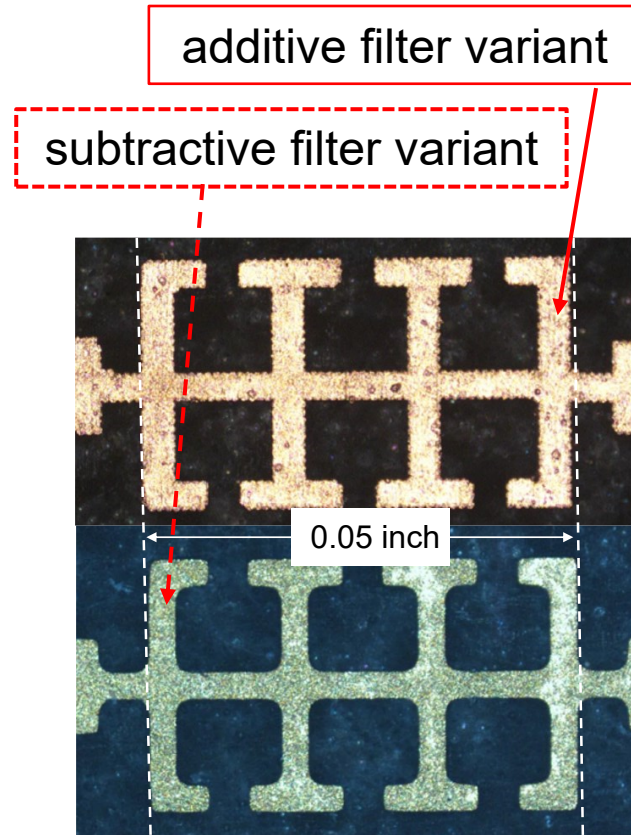
$$R_{q,eff,treated} = 0.86\mu\text{m} \pm 0.1\mu\text{m}$$

$$R_{q,eff,top\ side} = 0.44\mu\text{m} \pm 0.11\mu\text{m}$$

Excellent agreement  
between measurement  
and simulation



# Low-Pass Filters



**Main idea of the Gradient Model is adopted**  
**Surface impedance is calculated from real profiles**  
**An effective surface roughness parameter is introduced**  
**Profile approximations become obsolete**  
**Efficiency shown for additive/subtractive produced MS and filters**

# Thank you! Questions?